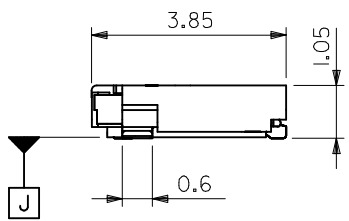
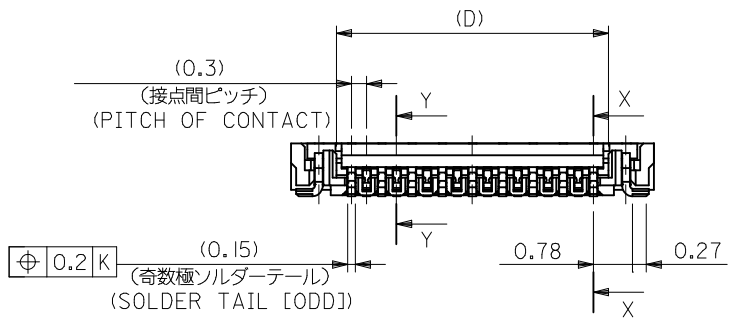


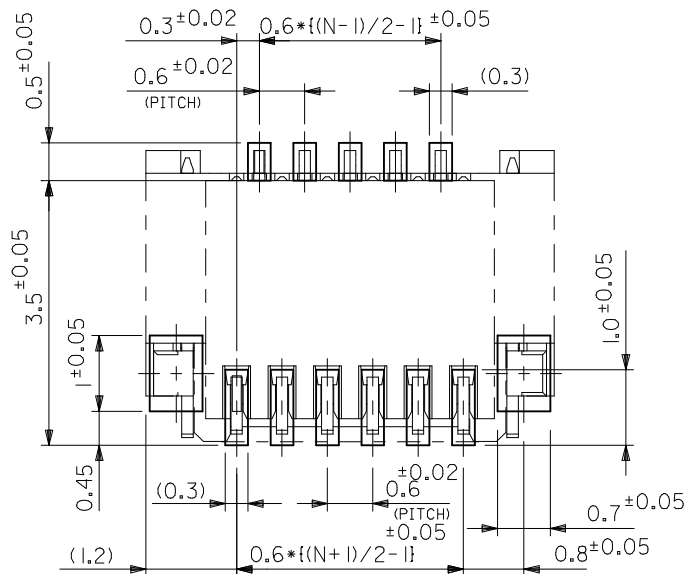
アクチュエータを開口した状態  
WHEN ACTUATOR IS OPENED



10.2	9.0	9.6	12.0	500797-3394	500797-3350	33
9.6	8.4	9.0	11.4	500797-3194	500797-3150	31
8.4	7.2	7.8	10.2	500797-2794	500797-2750	27
7.2	6.0	6.6	9.0	500797-2394	500797-2350	23
3.6	2.4	3.0	5.4	500797-1194	500797-1150	11
D	C	B	A	EMBOSSED TAPE ORDER No. オーダー番号	MATERIAL NO.	CKT.



REVISED EC NO: J2016-1099 DRWN:MTAKAHASHI 2016/04/19 CHKD:KTAHAKASHI 2016/04/26 APPR:KUSUHARA01 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY YMAEDA	DATE 2006/03/07	TITLE 0.3 FPC CONN E/O HSG ASSY (HGT=1.05MM) GOLD PLATING -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY MTANAKA	DATE 2006/03/07	<b>molex</b> DOCUMENT NO. SD-500797-005 SHEET NO. 1 OF 2	
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY NUKITA	DATE 2006/03/07		
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO.		SEE TABLE	
30 OVER		±0.25	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
	ANGULAR	±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				

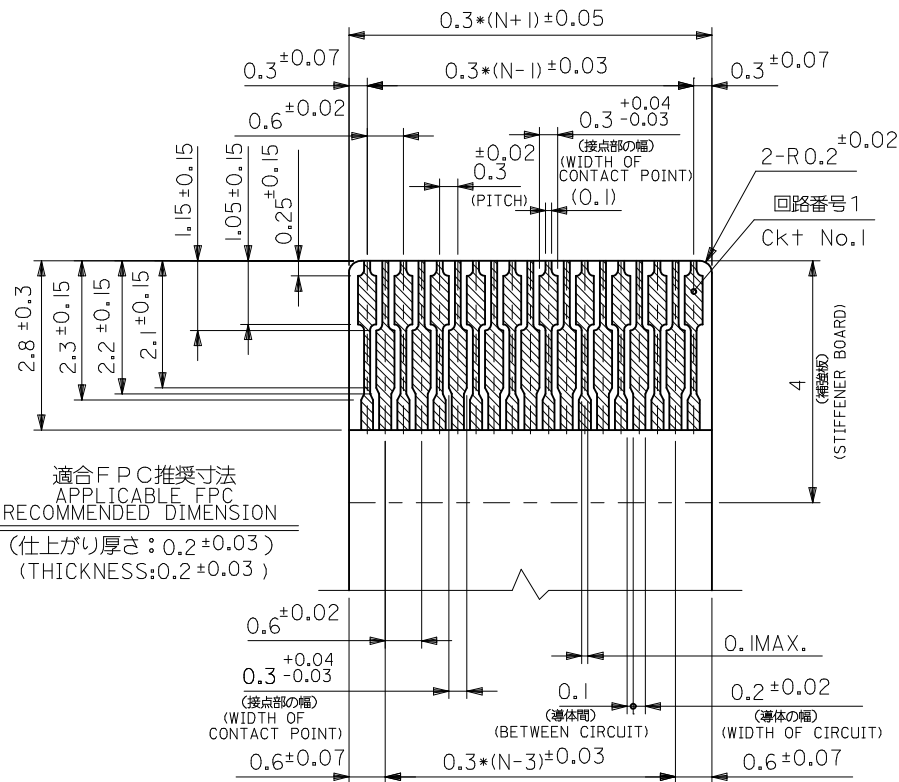


参考基板レイアウト図  
(マウント面)  
(MOUNTING SIDE)

注記 NOTES

1. 使用材料 MATERIAL  
 ハウジング : 液晶ポリマー ガラス充填 UL94V-0  
 HOUSING : LIQUID CRYSTAL POLYMER (GLASS FILLED) UL94V-0  
 アクチュエータ : 46 ナイロン ガラス充填 UL94V-0  
 ACTUATOR : 46 NYLON (GLASS FILLED) UL94V-0  
 ターミナル : 銅合金 (t=0.15), ニッケル下地金メッキ  
 TERMINAL : COPPER ALLOY, GOLD OVER NICKEL PLATING.  
 金具 : リン青銅 (t=0.15), ニッケル下地スズメッキ  
 FITTING NAIL : PHOSPHOR-BRONZE, TIN OVER NICKEL PLATING.  
 △ ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面  $\square$  に対し、  
 上方向 0.1MAXIMUM 下方向 0.15MAXIMUM とする。  
 又、相互のバラツキ量は 0.1MAXIMUM とする。  
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM  $\square$   
 UPPER DIRECTION : 0.1 MAXIMUM, LOWER DIRECTION : 0.15 MAXIMUM.  
 OFFSET BETWEEN SOLDER TAILS AND FITTING NAILS : 0.1 MAXIMUM.

適合FPC推奨寸法  
 APPLICABLE FPC  
 RECOMMENDED DIMENSION  
 (仕上がり厚さ: 0.2±0.03)  
 (THICKNESS: 0.2±0.03)



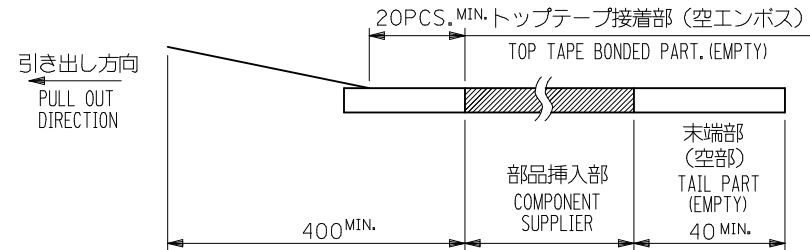
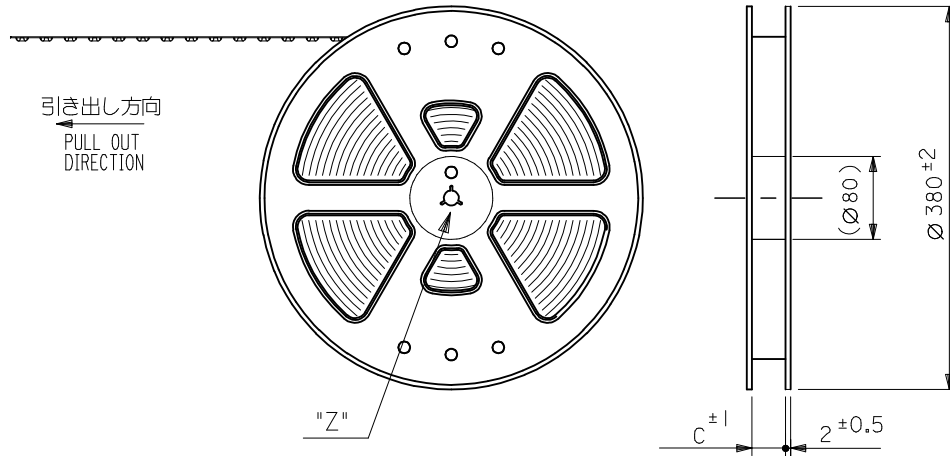
FPCについて:  
 打抜き方向は導体側から補強板側を推奨いたします。  
 導体部については軟銅箔35マイクロメートルまたは50マイクロメートルを  
 推奨致します。  
 補強フィルム材質はポリイミドを推奨します。  
 接着剤は熱硬化接着剤を推奨します。

ABOUT FPC  
 RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.  
 RECOMMENDED CONDUCTOR SPEC :  
 THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER  
 RECOMMENDED MATERIAL :  
 STIFFENER FILM : POLYIMIDE  
 BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO: J2016-1099 DRWN:MTAKAHASHI 2016/04/19 CHKD:KAKAHASHI 2016/04/26 APPR:TKUSUHARA01 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO. 500797-**50
	0.25 UNDER	UNDER	±0.03	DRAWN BY YMAEDA	DATE 2006/03/06	TITLE 0.3 FPC CONN E/O HSG ASSY (HGT=1.05MM) GOLD PLATING -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY MTANAKA	DATE 2006/03/06		
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY NUKITA	DATE 2006/03/06		
1.0 OVER	10 UNDER	±0.2	MATERIAL NO. SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
10 OVER	30 UNDER	±0.25	SIZE A3				
30 OVER		±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
J	REVISION						

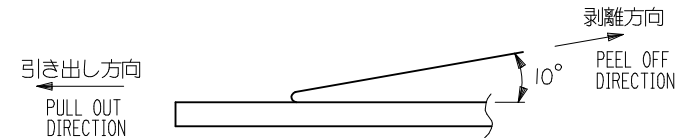
NOTES

- 製品詳細寸法については図面 SD-500797-005 を参照下さい。  
RE DETAILED DIMENSION, SEE SD-500797-005
- 梱包数量：3000個/リール  
NUMBER OF CONNECTORS : 3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

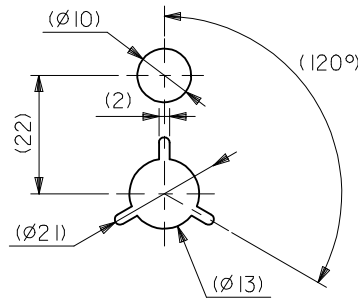


- トップテープの剥離強度：0.1N ~ 1.3N(10.2gf ~ 132.6gf)  
(剥離方向は下図参照)

尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)  
PEELING OFF FORCE OF TOP TAPE : 0.1N ~ 0.7N(10.2gf ~ 71.4gf)  
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.  
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.

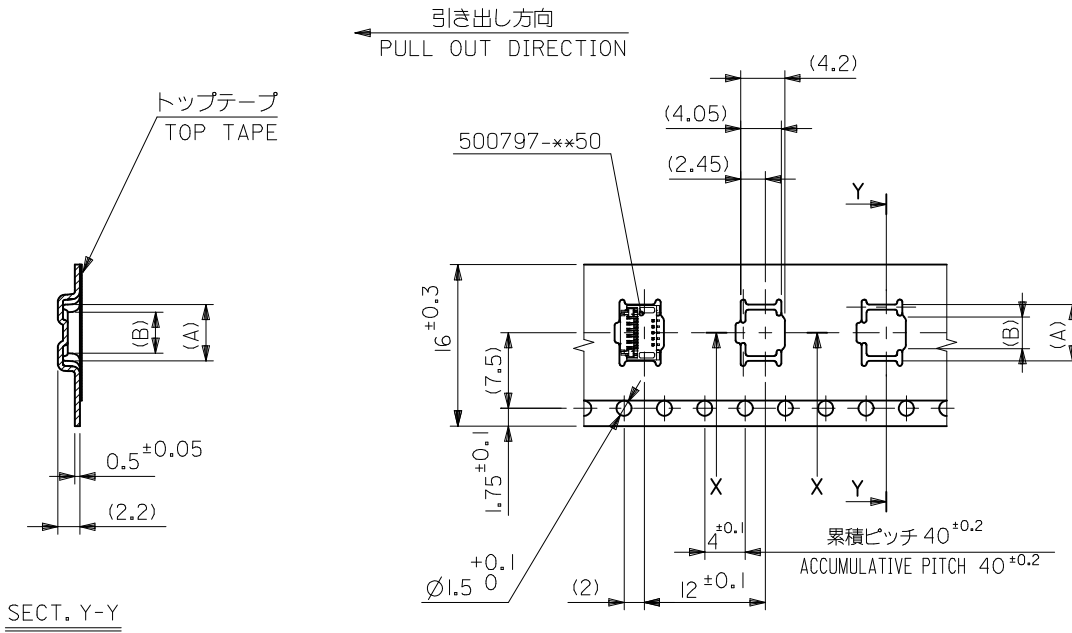


- 材料(MATERIAL)  
キャリアテープ(CARRIER TAPE)：ポリプロピレン(POLYPROPYLENE)  
トップテープ(TOP TAPE)：PET, PE, PEF  
リール(REEL)：ポリスチレン(PS) <リサイクル材含む>  
POLYSTYREN (PS) <RECYCLE MATERIAL CONTAINED>
- C寸法は SHEET 2 ~ 4 を参照下さい。  
SEE SHEET 2 ~ 4 (DIMENSION C).
- 欠品無きこと。  
THERE SHALL BE NO MISSING PRODUCTS.



DETAIL "Z"

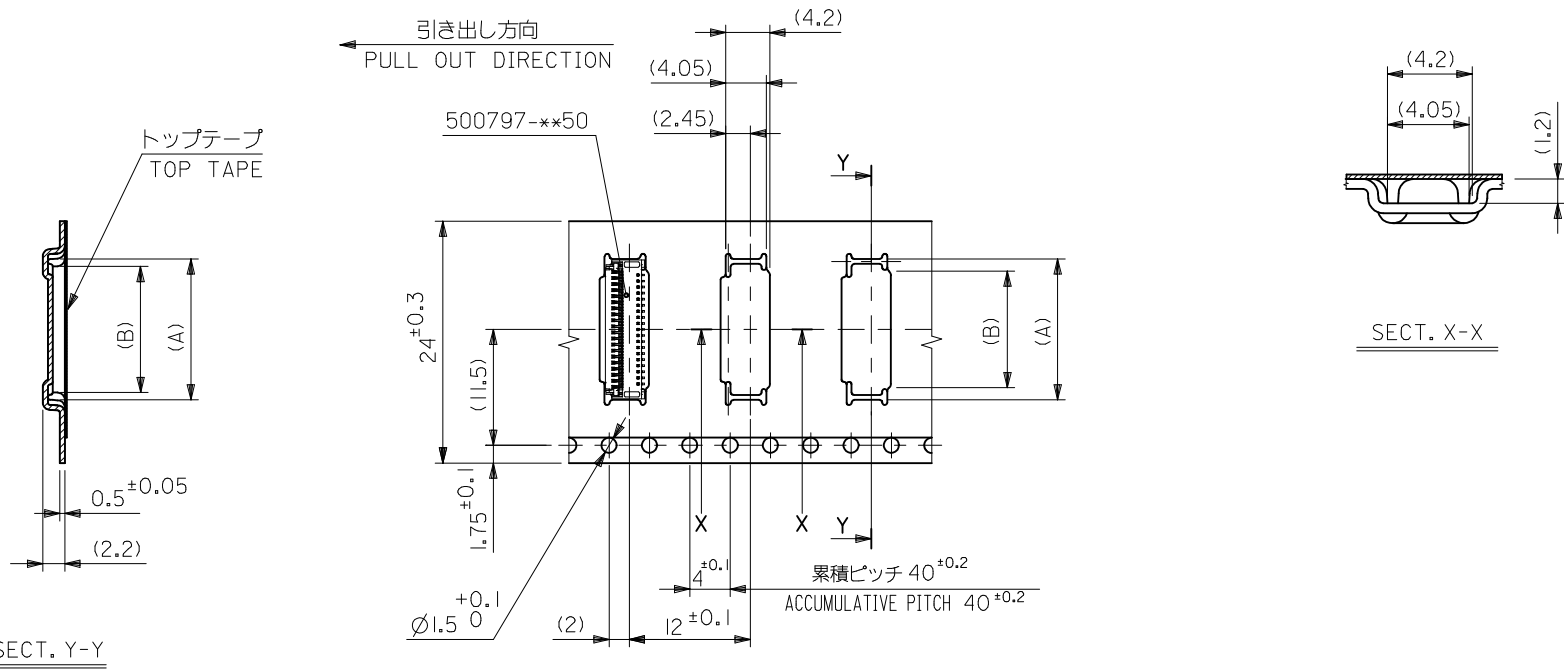
REVISED	EC NO: J2016-1099 DRWN:MTAKAHASHI 04/2016/04/19 CHKD:KATAHASHI 2016/04/26 APPR:KUSUHARA01 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	500797-**94	MODEL NO.	
				MM ONLY	---	DESIGN UNITS	THIRD ANGLE PROJECTION	
				DRAWN BY	DATE	TITLE		
				YMAEDA	2006/03/07	EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.05MM) GOLD PLATING -LEAD FREE-		
G	REV	0.25 UNDER UNDER ±0.03		CHECKED BY	DATE	DOCUMENT NO.		
		0.25 OVER 0.5 UNDER ±0.05		MTANAKA	2006/03/07			SD-500797-006
		0.5 OVER 1.0 UNDER ±0.1		APPROVED BY	DATE	SHEET NO.		
		1.0 OVER 10 UNDER ±0.2		NUKITA	2006/03/07		1 OF 3	
10 OVER 30 UNDER ±0.25		MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
30 OVER ±0.3		ANGULAR ±3 °		SIZE				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				A3				



16mm幅キャリアテープ  
16mm WIDTH CARRIER TAPE

16	17.5	3.4	5.6	500797-1194	11
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	製品番号 MATERIAL No.	極数 Ck+
				500797-**94	MODEL No.

REVISED EC NO: J2016-1099 DRWN:MTAKAHASHI 04/2016/04/19 CHKD:KATAHASHI 2016/04/26 APPR:KUSUHARA01 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY YMAEDA	DATE 2006/03/07	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.05MM) GOLD PLATING -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY MTANAKA	DATE 2006/03/07		
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY NUKITA	DATE 2006/03/07		
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO.		DOCUMENT NO.	SHEET NO.
10 OVER	30 UNDER	±0.25	SEE CHART		SD-500797-006	2 OF 3	
30 OVER		±0.3	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
	ANGULAR	±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				



24mm幅キャリアテープ  
24mm WIDTH CARRIER TAPE

24	25.5	10.0	12.2	500797-3394	33
		9.4	11.6	500797-3194	31
		8.2	10.4	500797-2794	27
		7.0	9.2	500797-2394	23
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	製品番号 MATERIAL No.	極数 Ck†
		500797-**-94		MODEL No.	

REVISED EC NO.: J2016-1099 DRWN:MTAKAHASHI 04/2016/04/19 CHKD:KTAHAKASHI 2016/04/26 APPR:TKUSUHARA01 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY YMAEDA	DATE 2006/03/07	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.05MM) GOLD PLATING -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY MTANAKA	DATE 2006/03/07		
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY NUKITA	DATE 2006/03/07		
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
10 OVER	30 UNDER	±0.25	SEE CHART		SD-500797-006		
30 OVER		±0.3	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
ANGULAR		±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				